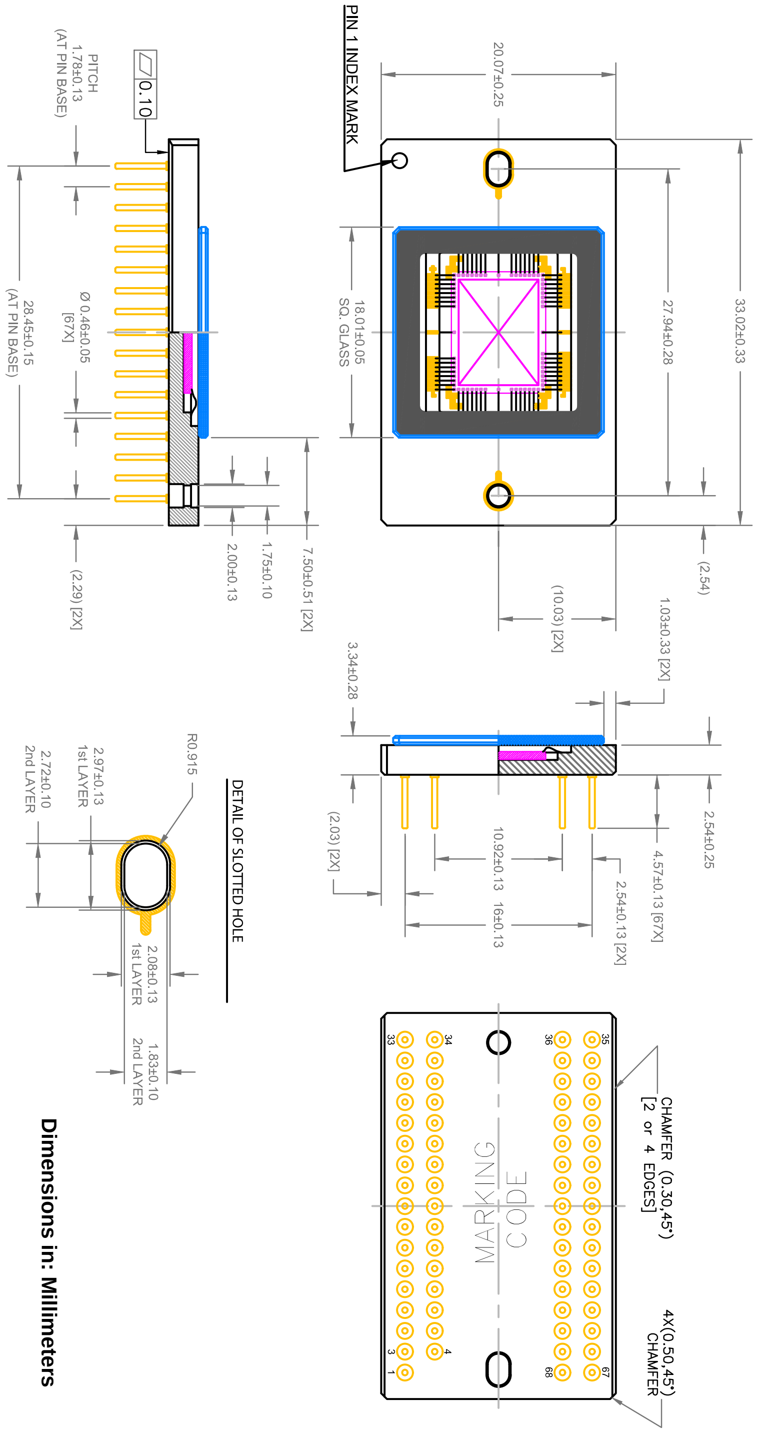
CPGA67, 33.02x20.07

CASE 107EH
ISSUE O

DATE 30 JUL 2014



Dimensions in: Millimeters

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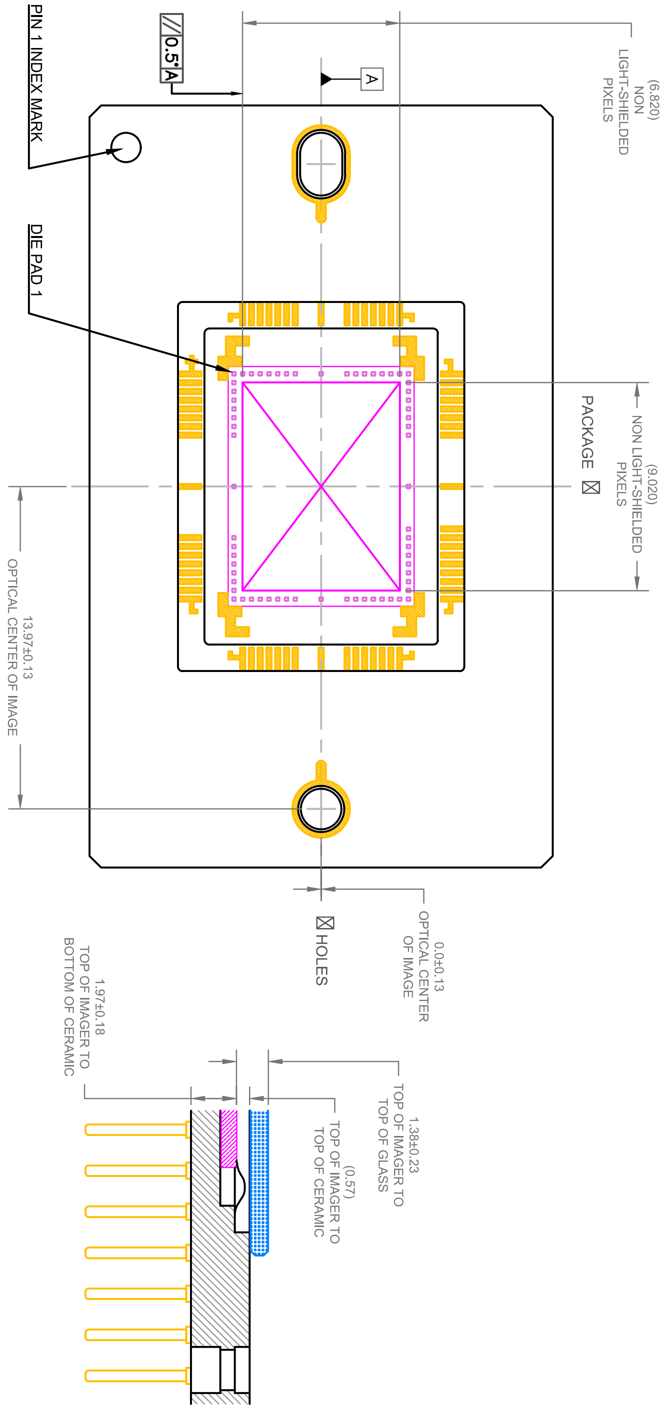

NOTES:
1. DIE IS THICKNESS OF PROCESSED 150MM WAFERS: 0.675 ±0.025 mm
2. STREETS ARE 100 µm WIDE AND CENTERS ARE SPACED (10.440, 8.110) mm ON WAFER.
3. SINGULATED DIE SIZE IS APPROXIMATELY (10.39 X 8.06) mm.
4. THE OPTICAL CENTER OF THE IMAGE IS AT THE CENTER OF THE DIE.

Dimensions in: Millimeters

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